

NEDER28.001APC



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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	Kuznetsov, et al.	) Group Art Unit Unknown
Appl. No.	:	Unknown	)
Filed	:	Herewith	) I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on
For	:	METHOD FOR TRANSFERRING WAFERS AND RING	) <u>11/16/01</u> (Date) <u>Gordon H. Olson</u> Gordon H. Olson, Reg. No. 20,319
Examiner	:	Unknown	)

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

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Dear Sir:

Prior to examination of the above-captioned application, please amend the application as follows:

IN THE SPECIFICATION:

Please amend the specification, published as International Application WO 00/68977, as follows:

On page 1, line 2, please insert --Field of the Invention--.

Please amend the paragraph beginning on page 1, line 3, as follows:

The present invention relates to a method of transferring a wafer between a thermal treatment chamber and a thermal treatment installation.

Background of the Invention

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FEB 20 2004  
GROUP 3600